



DATE 21 MAY 2021

NOTES:

- A. PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. BA, DATED OCTOBER 2002CONTROLLING
- B. ALL DIMENSIONS ARE IN MILLIMETERS.C. DIMENSIONS DO NOT INCLUDE BURRS
- OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.

	14.0101-20			
ЫМ	MILLIMETERS			
Biw	MIN.	NOM.	MAX.	
А	0.70	0.75	0.80	
A1	0.00	-	0.05	
A3	0.20 REF			
b	0.27	0.32	0.37	
D	3.20	3.30	3.40	
D2	1.18	1.28	1.38	
D3	1.18	1.28	1.38	
E	3.20	3.30	3.40	
E2	1.76	1.86	1.96	
E3	0.45 REF			
E4	0.15	0.20	0.25	
е	0.65 BSC			
e/2	0.325 BSC			
k	0.33 REF			
L	0.85	0.95	1.05	
L4	0.10	0.20	0.30	
z	0.52 REF			

BOTTOM VIEW

DOCUMENT NUMBER:	98AON13676G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	PQFN8 3.3X3.3, 0.65P		PAGE 1 OF 1		
onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.					